

**RoHS SIDACtor® Series - DO-15**



**Agency Approvals**

Agency	Agency File Number
	E133083

**Pinout Designation**

Not Applicable

**Schematic Symbol**



**Description**

The SIDACtor Series DO-15 are designed to protect baseband equipment such as modems, line cards, CPE and DSL from damaging overvoltage transients.

The series provides a cost-effective through-hole solution that enables equipment to comply with global regulatory standards.

**Features and Benefits**

- Low voltage overshoot
- Low on-state voltage
- Does not degrade with use
- Fails short circuit when surged in excess of ratings
- Low Capacitance

**Applicable Global Standards**

- TIA-968-A
- TIA-968-B
- ITU K.20/21 Enhanced Level\*
- ITU K.20/21 Basic Level
- GR 1089 Inter-building\*
- GR 1089 Intra-building
- IEC 61000-4-5
- YD/T 1082
- YD/T 993
- YD/T 950

\* A/B-rated parts require series resistance

**Electrical Characteristics**

Part Number	Marking	$V_{DRM}$	$V_s$	$I_H$	$I_s$	$I_T$	$V_T$	Capacitance	
		@ $I_{DRM}=5\mu A$	@ 100V/ $\mu s$	mA min	mA max	A max	@ $I_T=2.2$ Amps	@ 1MHz, 2V bias	
		V min	V max				V max	pF min	pF max
P1100GALRP	P11A	90	130	150	800	2.2	5	30	60
P1300GALRP	P13A	120	160	150	800	2.2	5	25	40
P1500GALRP	P15A	140	180	150	800	2.2	5	25	40
P1800GALRP	P18A	170	220	150	800	2.2	5	25	40
P2300GALRP	P23A	190	260	150	800	2.2	5	25	30
P2600GALRP	P26A	220	300	150	800	2.2	5	25	30
P3100GALRP	P31A	275	350	150	800	2.2	5	20	30
P3500GALRP	P35A	320	400	150	800	2.2	5	20	30
P1100GBLRP	P11B	90	130	150	800	2.2	5	30	60
P1300GBLRP	P13B	120	160	150	800	2.2	5	25	40
P1500GBLRP	P15B	140	180	150	800	2.2	5	25	40
P1800GBLRP	P18B	170	220	150	800	2.2	5	25	40
P2300GBLRP	P23B	190	260	150	800	2.2	5	25	30
P2600GBLRP	P26B	220	300	150	800	2.2	5	25	30
P3100GBLRP	P31B	275	350	150	800	2.2	5	20	30
P3500GBLRP	P35B	320	400	150	800	2.2	5	20	30

Notes:  
 - Absolute maximum ratings measured at  $T_a = 25^\circ C$  (unless otherwise noted).  
 - Devices are bi-directional.

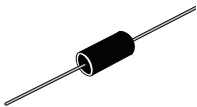
**Surge Ratings**

Series	$I_{PP}$		$I_{TSM}$
	10x560 <sup>1</sup> 10x560 <sup>2</sup>	10x1000 <sup>1</sup> 10x1000 <sup>2</sup>	50 / 60 Hz
	Amps min	Amps min	Amps min
A	50	45	20
B	100	80	25

Notes:

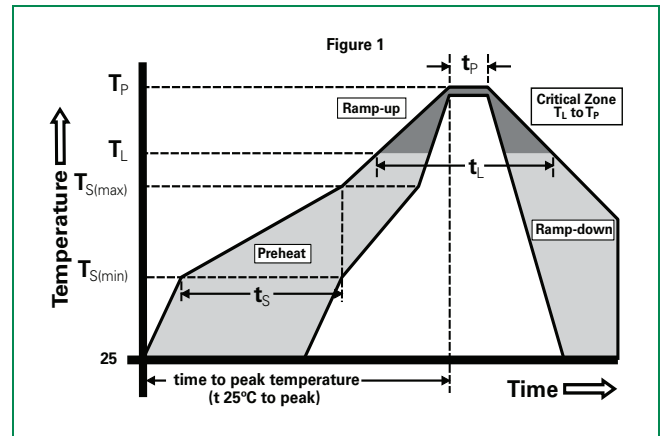
- 1 Current waveform in  $\mu s$
- 2 Voltage waveform in  $\mu s$
- Peak pulse current rating ( $I_{PP}$ ) is repetitive and guaranteed for the life of the product.
- $I_{PP}$  ratings applicable over temperature range of -40 to +85°C
- The device must initially be in thermal equilibrium with -40°C  $\leq T_J \leq$  +150°C

**Thermal Considerations**

Package	Symbol	Parameter	Value	Unit
 DO-15	$T_J$	Operating Junction Temperature Range	-40 to +150	°C
	$T_S$	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	60	°C/W

**Soldering Parameters**

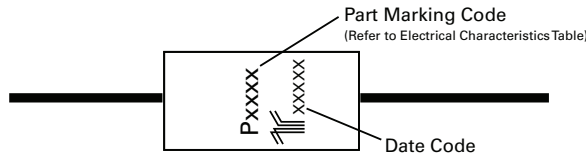
Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	- Temperature Min ( $T_{s(min)}$ )	+150°C
	- Temperature Max ( $T_{s(max)}$ )	+200°C
	- Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/sec. Max.
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max.
Reflow	- Temperature ( $T_L$ ) (Liquidus)	+217°C
	- Temperature ( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp ( $T_p$ )		8 min. Max.
Do not exceed		+260°C



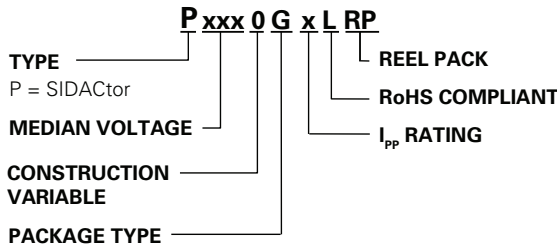
**Physical Specifications**

<b>Lead Material</b>	Copper Alloy
<b>Terminal Finish</b>	100% Matte-Tin Plated
<b>Body Material</b>	UL recognized epoxy meeting flammability classification 94V-0

**Part Marking**



**Part Numbering**



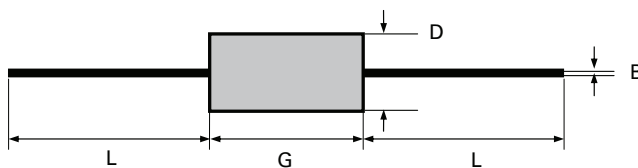
**Environmental Specifications**

<b>High Temp Voltage Blocking</b>	80% Rated $V_{DRM}$ ( $V_{AC}$ Peak) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
<b>Temp Cycling</b>	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A104
<b>Biased Temp &amp; Humidity</b>	52 $V_{DC}$ (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
<b>High Temp Storage</b>	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
<b>Low Temp Storage</b>	-65°C, 1008 hrs.
<b>Thermal Shock</b>	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
<b>Autoclave (Pressure Cooker Test)</b>	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
<b>Resistance to Solder Heat</b>	+260°C, 30 secs. MIL-STD-750 (Method 2031)
<b>Moisture Sensitivity Level</b>	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

**Packing Options**

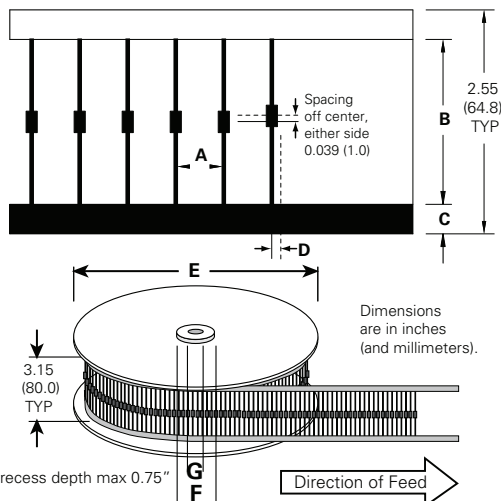
Package Type	Description	Quantity	Added Suffix	Industry Standard
G	DO-15 Axial Tape & Reel	5000	RP	EIA-RS-296-D

**Dimensions — DO-15**



Dimension	Inches		Millimeters	
	MIN	MAX	MIN	MAX
<b>B</b>	0.028	0.034	0.711	0.864
<b>D</b>	0.12	0.14	3.048	3.556
<b>G</b>	0.235	0.27	5.969	6.858
<b>L</b>	1		25.4	

**Tape and Reel Specification — DO-15**



Symbols	Description	Inches	MM
<b>A</b>	Component Spacing (lead to lead)	0.200 ± 0.020"	5.08 ± 0.508
<b>B</b>	Inner Tape Pitch	2.062 ± 0.059"	52.37 ± 1.498
<b>C</b>	Tape Width	0.250"	6.35
<b>D</b>	Max. Off Alignment	0.048"	1.219
<b>E</b>	Reel Dimension	13"	330.2
<b>F</b>	Max. Hub Recess	3"	76.19
<b>G</b>	Max. Arbor Hole	0.68"	17.27